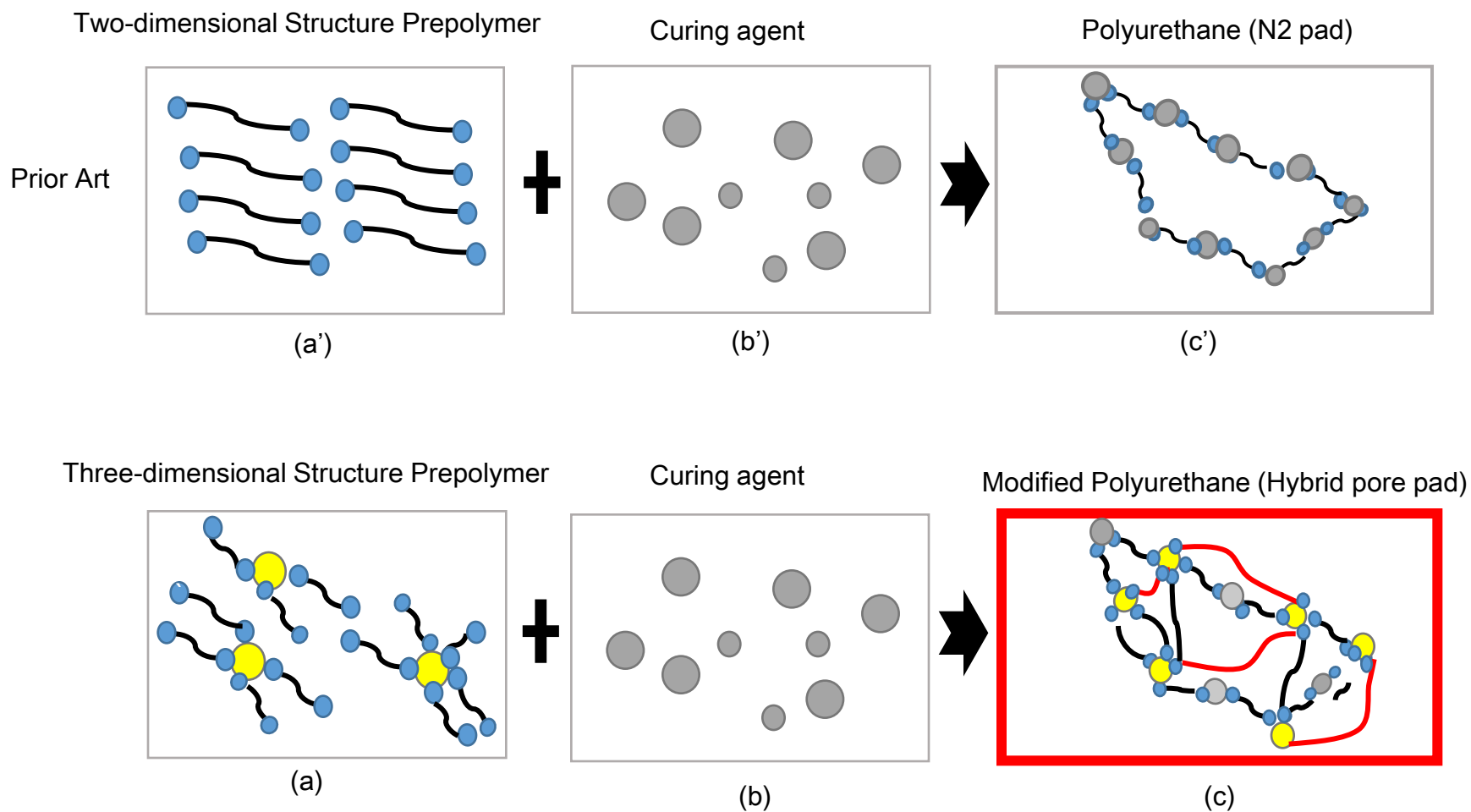
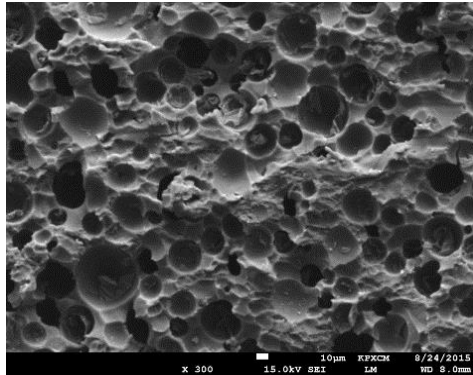


【Fig. 3】

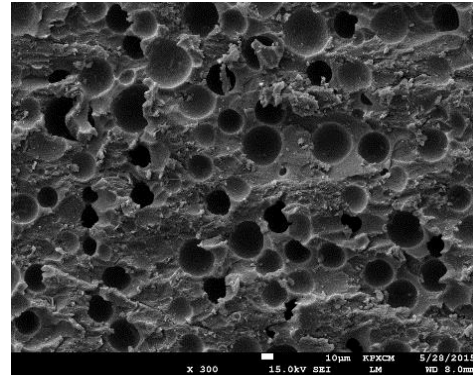


Before CMP

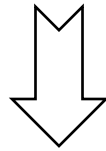
【Fig. 4】



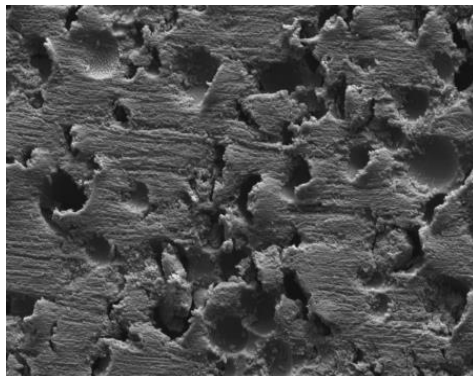
(a')



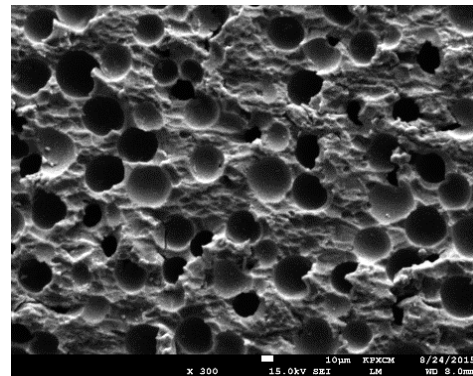
(a)



After CMP

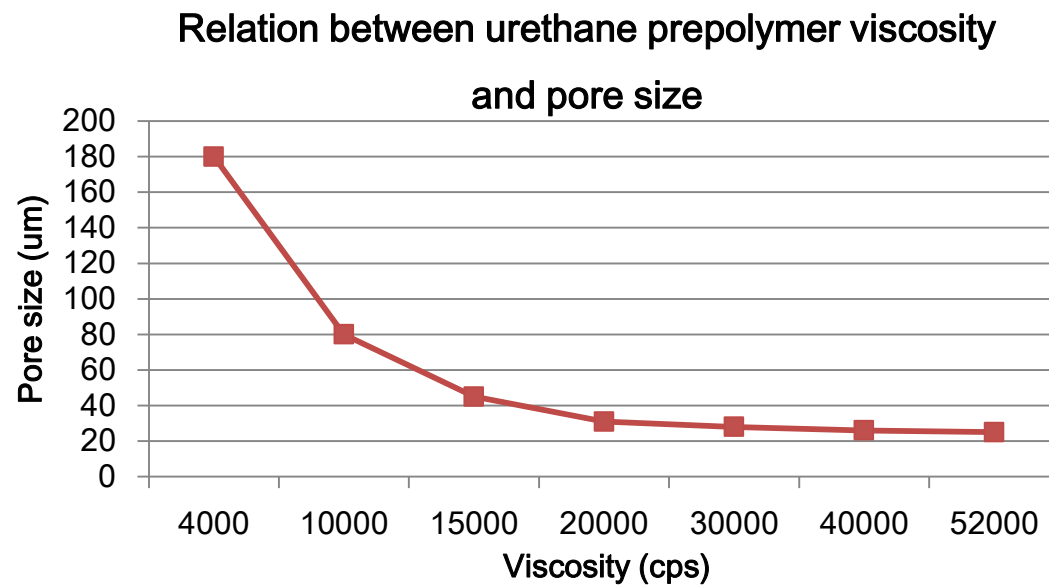


(b')

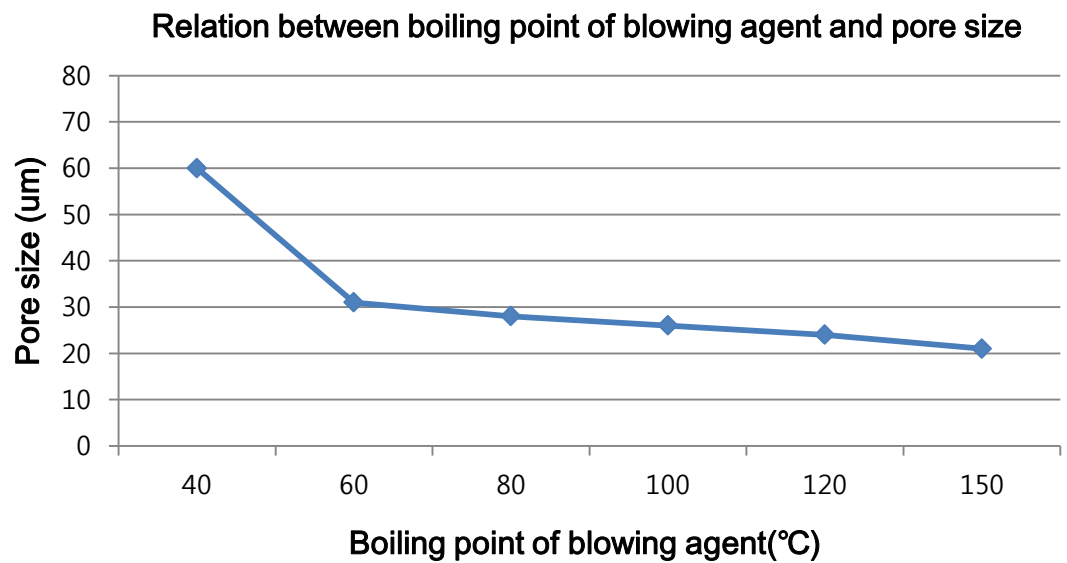


(b)

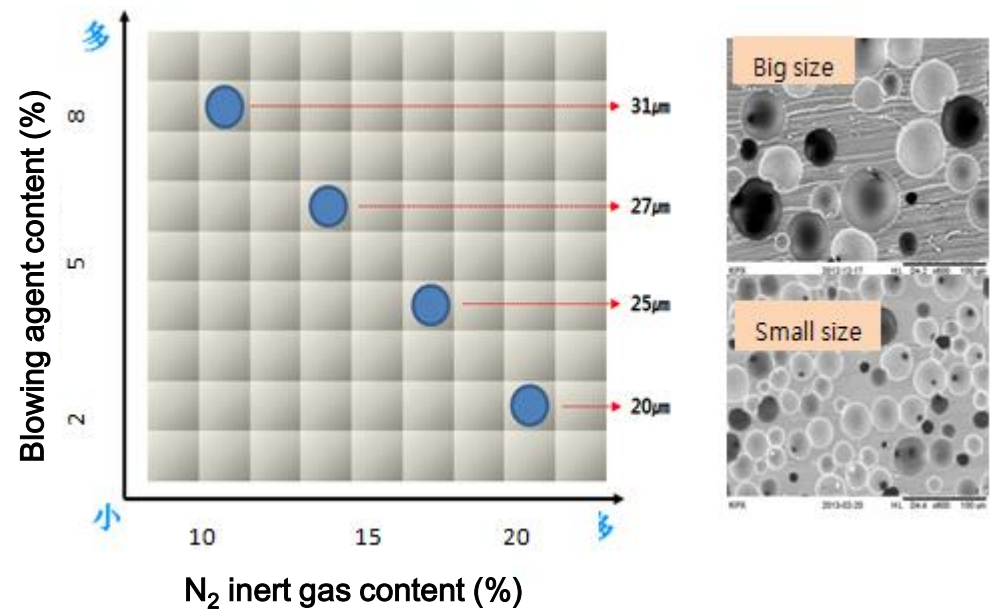
【Fig. 5】



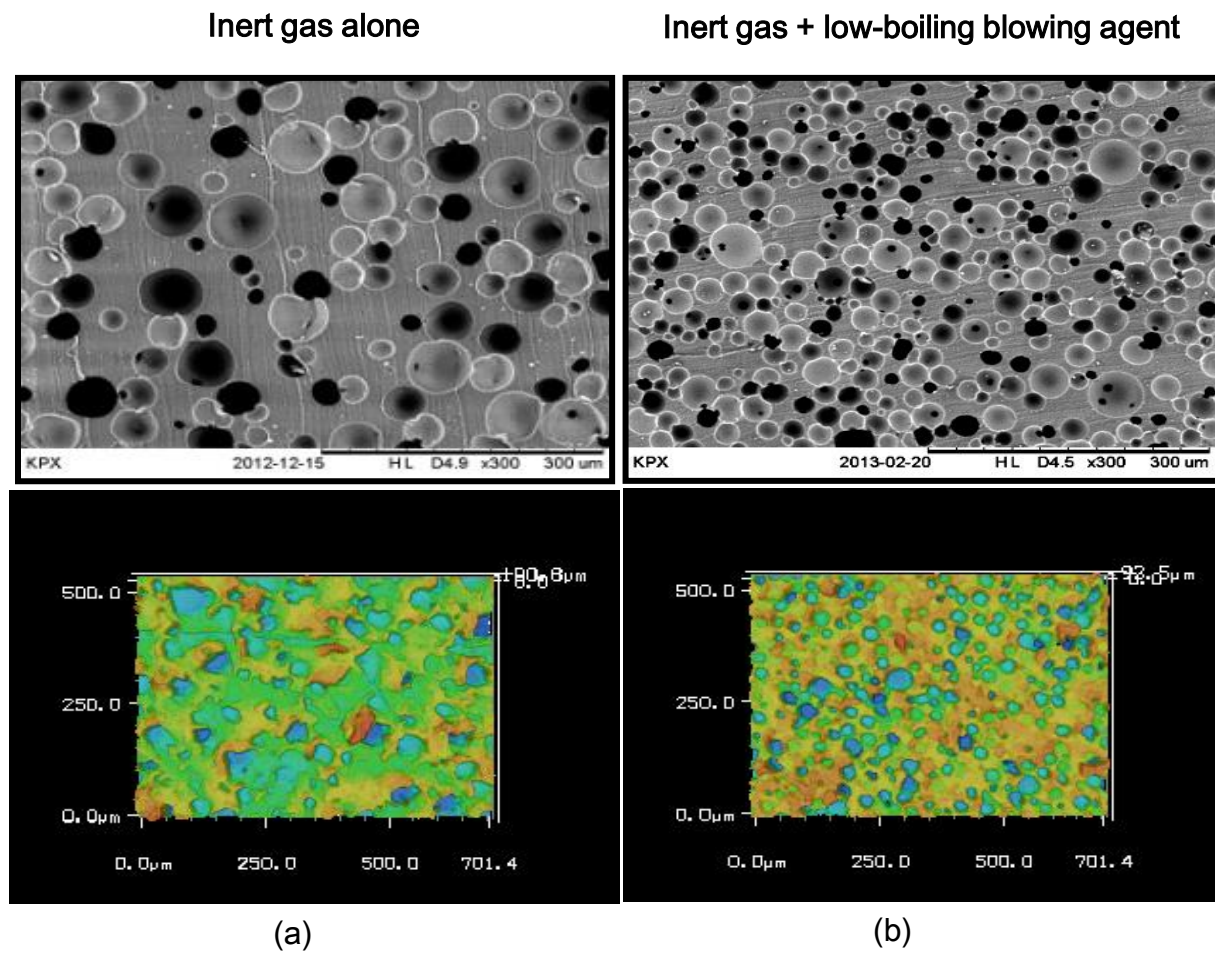
【Fig. 6】



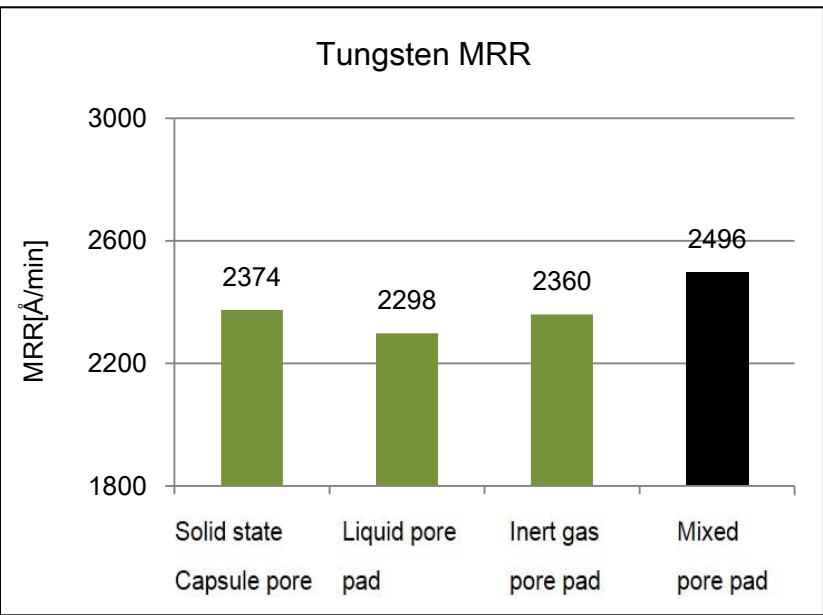
【Fig. 7】



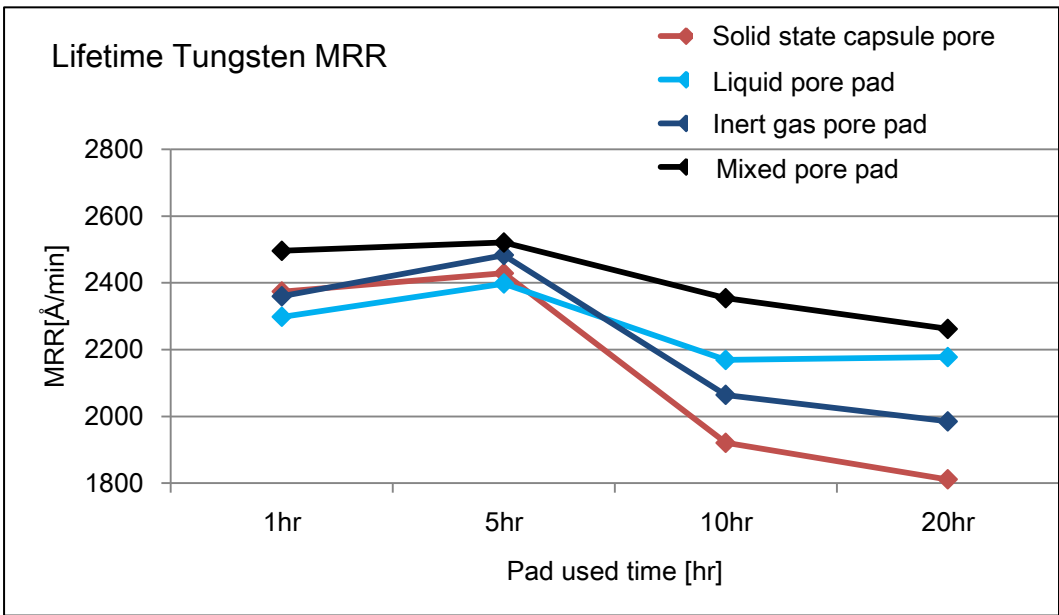
【Fig. 8】



【Fig. 9】



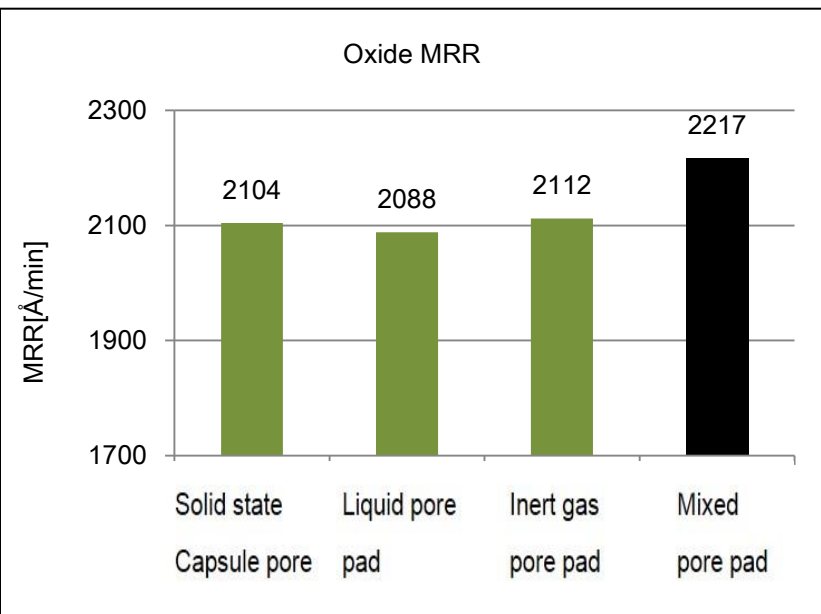
(a)



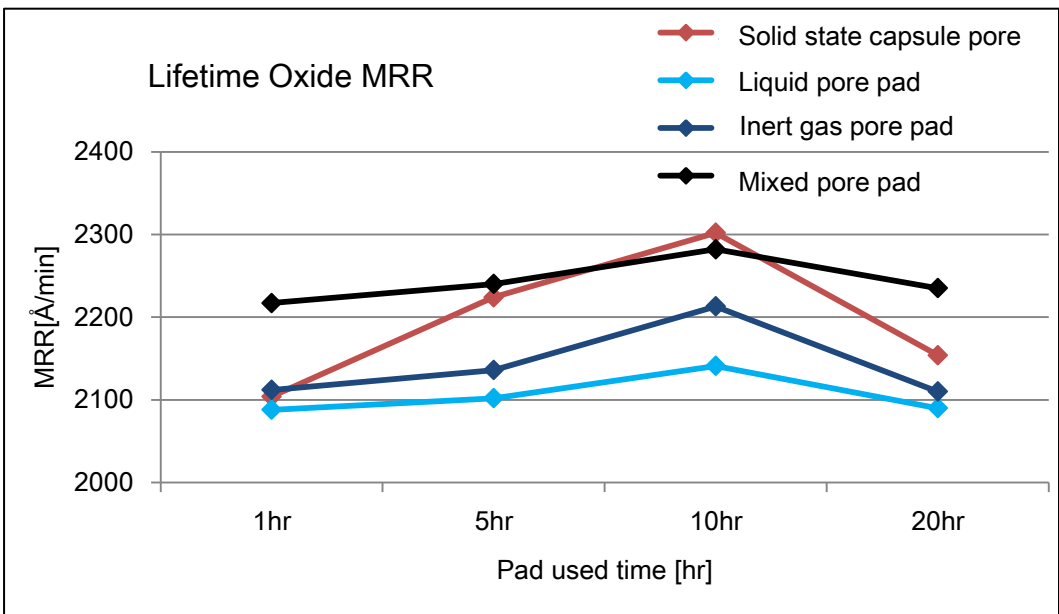
(b)

Apparatus	Wafer	Slurry	Disk
POLI-762	Tungsten	W	C1

【Fig. 10】



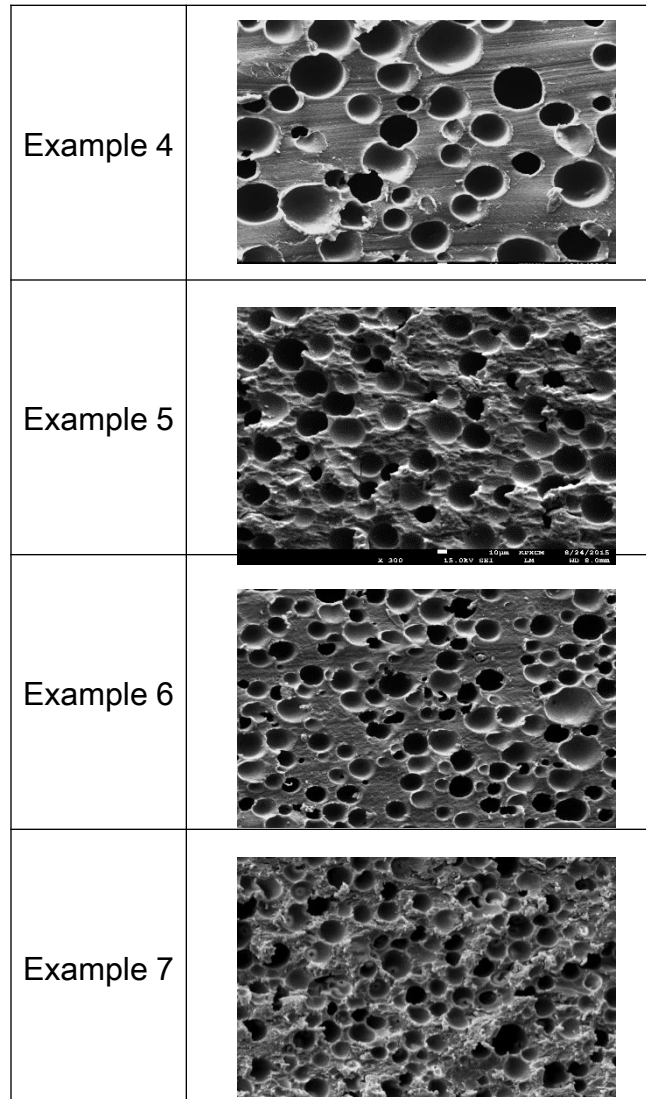
(a)



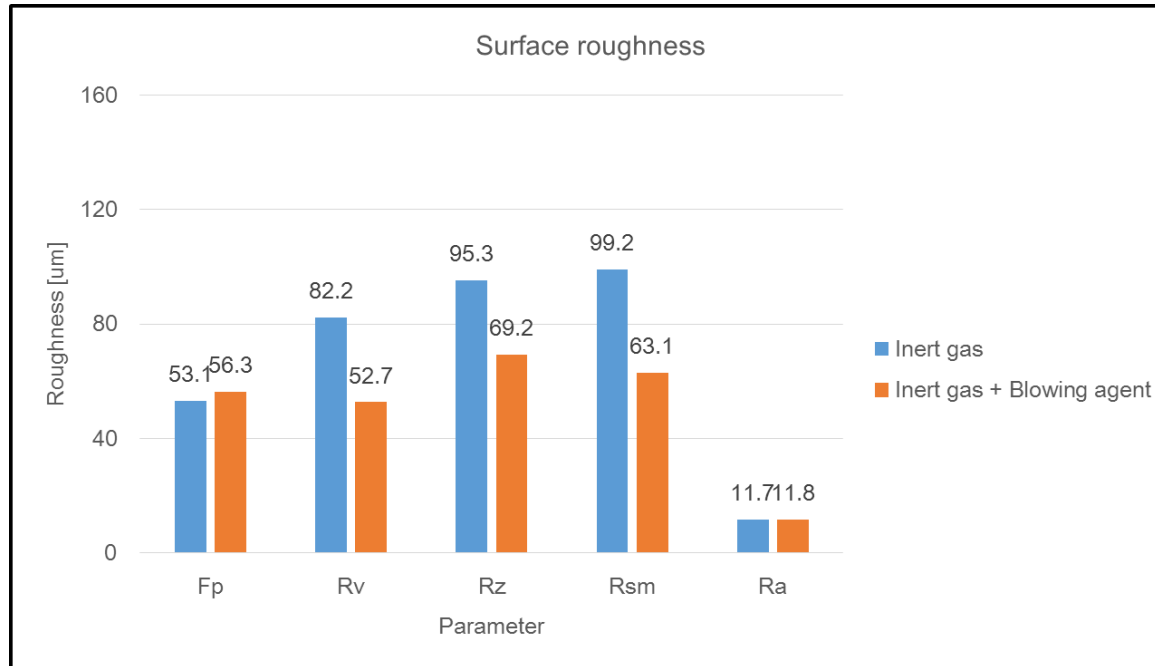
(b)

Apparatus	Wafer	Slurry	Disk
POLI-762	Oxide	T	C7

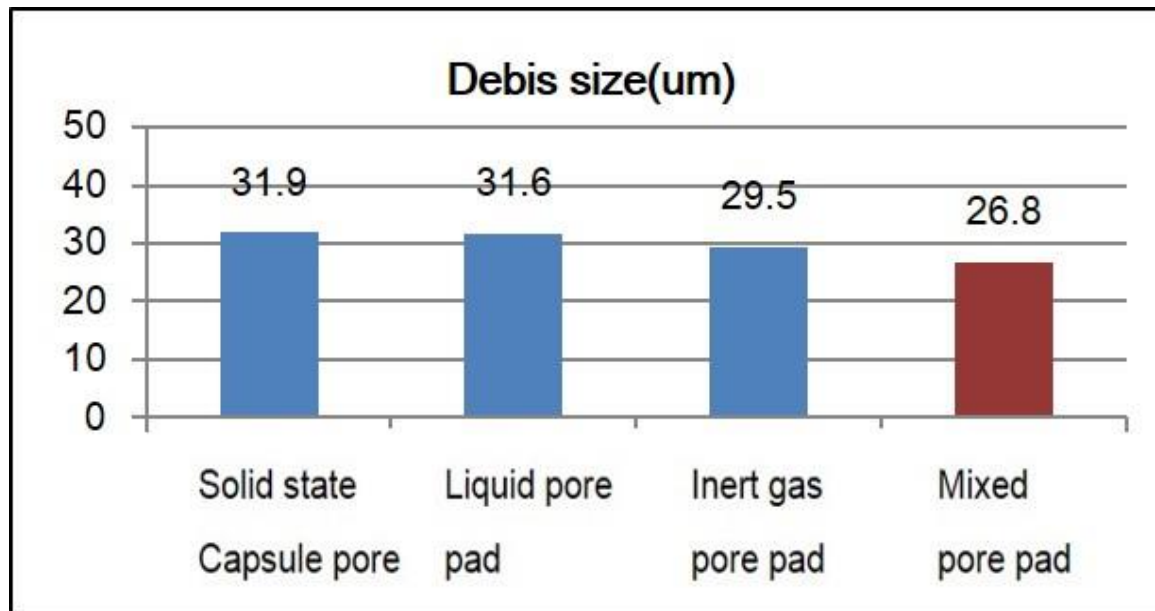
【Fig. 11】



【Fig. 12 (a)】



【Fig. 12 (b)】



【Fig. 12 (c)】

